

PCN Number:	20210727000.1	PCN Date:	July 28, 2021
Title:	Qualification of MIHO8 as an additional Fab site option for select LBC7 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Oct 28, 2021	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input checked="" type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its MIHO8 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
RFAB	LBC7	300 mm	MIHO8	LBC7	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
MIHO8	MH8	JPN	Ibaraki

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750




(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

BQ25890HRTWR	BQ25890HRTWT
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Qualification Report

Approve Date 23-Jul-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25890HRTW	QBS Product Reference: BQ25890HRTW	QBS Process Reference: TP562110R9A
AC	Autoclave 121C	96 Hours	-	-	3/231/0
CDM	ESD - CDM	1000 V	-	1/3/0	-
CDM	ESD - CDM	1500 V	1/3/0	-	-
CDM	ESD-CDM	500 V	-	-	3/9/0
ELFR	Early Life Failure Rate, 140C	48 Hours	-	-	3/1881/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HBM	ESD - HBM	2500 V	-	1/3/0	-
HBM	ESD - HBM	4000 V	1/3/0	-	-
HBM	ESD-HBM	2000 V	-	-	3/9/0
HTOL	Life Test, 140C	480 Hours	-	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0
LU	Latch-up	(Per JESD78, Class I)	1/6/0	1/6/0	-
LU	Latch-up	(Per JESD78, Class II)	1/6/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0

- QBS: Qual By Similarity

- Qual Device BQ25890HRTW is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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